

Supplier Name: Texas Instruments Inc. (DUNS# 00-732-1904)
 Contact Info: ti.com/support
 Form/Declaration Type: Distribute - RoHS and IEC 62474 DB
 Created on: 06/01/2022

Details for "LM4140CCMX-2.5/NOPB"

Current Product Information

TI part number	Lead finish/Ball material	MSL rating/peak reflow	Assembly site	Package Pins	Package body size (mm)	Total device mass (mg)*
LM4140CCMX-2.5/NOPB	SN	Level-1-260C-UNLIM	Texas Instruments Electronics	D 8	4.9 x 3.9 x 1.75	82.4

*Total Device Mass
 The summary mass is a rounded value and will be within approximately +/- 10% of the detailed mass value.

Environmental Ratings Information

RoHS	REACH	Green	IEC 62474 DB
Yes	Yes	Yes	Yes

Component Information

Component	Substance	CAS Number	Amount (mg)	Homogeneous Material Level		Component Level	
				Percentage %	ppm	Percentage %	ppm
Bond Wire							
Precious Metals	Gold	7440-57-5	0.129942	100	1000000	0.157706	1577
Sub-Total			0.129942	100	1000000	0.157706	1577
Die Attach Adhesive							
Precious Metals	Silver	7440-22-4	0.14175	75	750000	0.172037	1720
Thermoplastics	Epoxy	85954-11-6	0.04725	25	250000	0.057346	573
Sub-Total			0.189	100	1000000	0.229383	2294
Die Attach Adhesive 2							
Precious Metals	Silver	7440-22-4	0.186629	74.9999	749999	0.226505	2265
Thermoplastics	Epoxy	85954-11-6	0.06221	25.0001	250001	0.075502	755
Sub-Total			0.248839	100	1000000	0.302007	3020
Lead Frame							
Copper and Its Alloys	Copper	7440-50-8	20.03484	96.6	966000	24.315607	243156
Copper and Its Alloys	Iron	7439-89-6	0.493612	2.38	23800	0.59908	5991
Copper and Its Alloys	Phosphorus	7723-14-0	0.006222	0.03	300	0.007551	756
Precious Metals	Silver	7440-22-4	0.180438	8700	8700	0.218991	2190
Zinc and Its Alloys	Zinc	7440-66-6	0.024888	0.12	1200	0.030206	302
Sub-Total			20.74	100	1000000	25.171436	251714
Lead Frame Plating							
Other Nonferrous Metals and Alloys	Tin	7440-31-5	1.6	100	1000000	1.941866	19419
Sub-Total			1.6	100	1000000	1.941866	19419
Mold Compound							
Other Inorganic Materials	Fused Silica	60676-86-0	50.836007	89	890000	61.697941	616979
Other Nonferrous Metals and Alloys	Metal Hydroxide	Trade Secret	1.713573	3	30000	2.079706	20797
Thermoplastics	Epoxy	85954-11-6	4.569529	8	80000	5.545883	55459
Sub-Total			57.119109	100	1000000	69.32353	693235
Semiconductor Device							
Ceramics / Glass	Doped Silicon	7440-21-3	1.022224	100	1000000	1.240639	12406
Sub-Total			1.022224	100	1000000	1.240639	12406
Semiconductor Device 2							
Ceramics / Glass	Doped Silicon	7440-21-3	1.345867	100	1000000	1.633433	16334
Sub-Total			1.345867	100	1000000	1.633433	16334
Total			82.394981			100	1000000

Important Note
 The ppm calculations are at the **homogeneous material** level and are maximum concentration values. The ppm displayed represents the **homogeneous material** with the highest ppm for that substance. The amount (mg) calculations represent the maximum total amount of each substance within the component.
 The ppm calculations are at the **component** level and are average concentration values. The amount (mg) calculations represent the average total amount of each substance within the **component**.
[See Glossary of Terms for more details.](#)

Important Part Information
 There is a remote possibility the Customer Part Number (CPN) your company uses could reference more than one TI part number. This is due to two or more users (EMSI or subcontractors) using the same CPN for different TI part numbers. If this occurs, please check your Customer Part Number and cross reference it with the TI part number seen on this page.

Product Content Methodology
[For an explanation of the methods used to determine material weights, See Product Content Methodology](#)

Material Declaration Certificate for Semiconductor IC Packaged Products

TI certifies that the material content information provided by TI is representative and accurate to the best of their knowledge based on material information provided by its suppliers and their combination into finished IC packaged products. TI semiconductor products designated to be "Pb-free", "Green" or "RoHS Exempt" fully meets the latest EU RoHS Directive requirements along with other legislation as seen in the former JIG-101 list that has been transferred to the IEC 62474 database.

Important Information/Disclaimer

TI bases its material content information on information provided by third-party suppliers and has taken, and continues to take, reasonably diligent steps to provide any required or available information. TI may not have conducted destructive testing or chemical analysis on incoming materials and chemicals. TI and TI suppliers may consider certain information to be proprietary, and thus certain information may not be available for release by TI. The material content information is provided by TI "as is."
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Signature: [\(click here for a fuller statement with a signed certificate\)](#)

Name/Title: Hubie Payne, Vice President, Worldwide SC Quality
 For further environmental statements, please go to www.ti.com/ecoinfo
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RoHS: Means TI semiconductor products that are compliant with the current RoHS requirement that the maximum concentration values of the ten substances listed in RoHS Annex II do not exceed 0.1 % by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI semiconductor products labeled as "RoHS Compliant" are suitable for use in specified lead-free processes. TI may also reference these types of semiconductor products as "Pb-Free." These TI semiconductor products are also fully compliant with GADSL and the IEC 62474 database for electronic requirements.

RoHS Exempt: Means TI semiconductor products that contain lead (Pb) above the RoHS Annex II threshold, but that fall within one of the specific RoHS exemptions noted above or documented in <http://www.ti.com/lit/pdf/szzq088>

Green: Means the content of Chlorine (Cl) and Bromine (Br)-based flame retardants meet JS709B low halogen requirements of <=1 000ppm threshold; Antimony trioxide (Sb2O3) contained in halogen based flame retardant materials meets the <=1 000ppm threshold requirement; and Beryllium Oxide (BeO) is <=1000ppm.